Rev 2.0, 07.06.2019

LED1050G-03

- Infrared LED
- 1050 nm, 15 mW
- Chip: GaAs, 300 x 300 μm
- 5 mm Clear Molding, Epoxy Resin
- Viewing Angle: 24°









Description

LED1050G-03 contains one GaAs LED chip die mounted on a lead frame hermetically sealed with a clear epoxy lens.

On forward bias, it emits a power radiation of typical 15 mW at a peak wavelength at 1050 nm.

Maximum Ratings (TCASE=25°C)

D		Val	11.25		
Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	P_D		130	mW	
Forward Current	IF		100	mA	
Pulse Forward Current *1	I FP		1000	mA	
Reverse Voltage	VF		5	V	
Thermal Resistance	RTHJA		300	K/W	
Junction Temperature	TJ		120	°C	
Operating Temperature	TCASE	- 40	+ 100	°C	
Storage Temperature	T _{STG}	- 40	+ 100	°C	
Lead Solder Temperature *2	T _{SLD}		+ 265	°C	

^{*1} duty=1%, pulse width = 10 μ s

Electro-Optical Characteristics (TCASE=25°C)

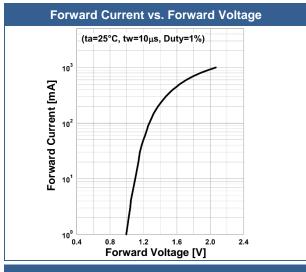
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	λ_P	I _F =50mA	1000		1100	nm
Half Width	$\Delta \lambda$	I _F =50mA		42		nm
Forward Voltage	V_F	I _F =50mA		1.2	1.3	V
	V_{FP}	I _{FP} =500mA		2.1		
Radiated Power *1	Po	I _F =50mA		15		mW
		I _{FP} =500mA		130		
Radiant Intensity *2	IE	I _F =50mA		73		mW/sr
		I _{FP} =500mA		650		
Viewing Angle	φ	I _F =50mA		24		deg.
Rise Time	t_R	I _F =50mA		30		ns
Fall Time	t _F	I _F =50mA		30		ns

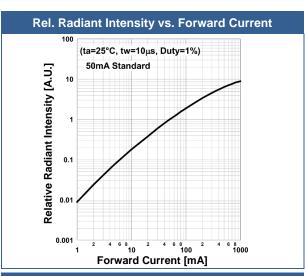
^{*1} measured by G8370-85

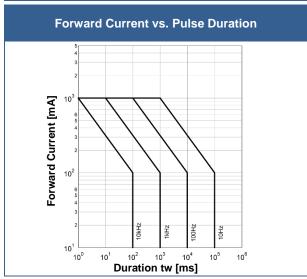
^{*2} must be completed within 3 seconds

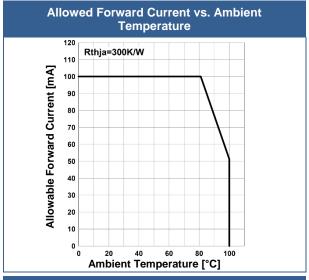
^{*2} measured by Ando Optical Multi Meter AQ2140 & AQ2742

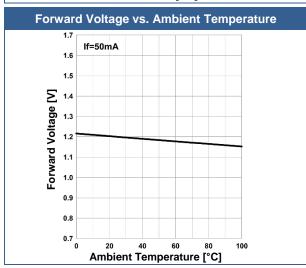
Typical Performance Curves

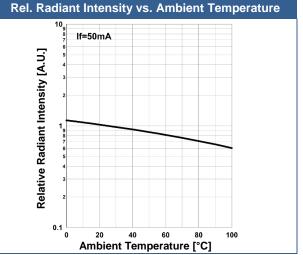










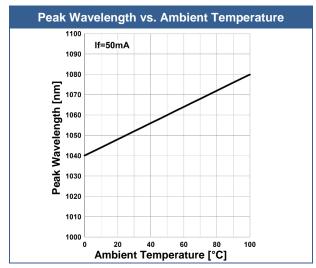


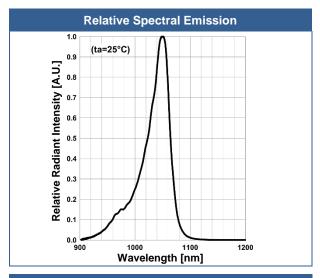


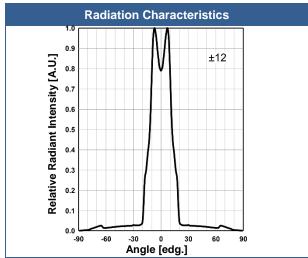
ROITHNER LASERTECHNIK GMBH

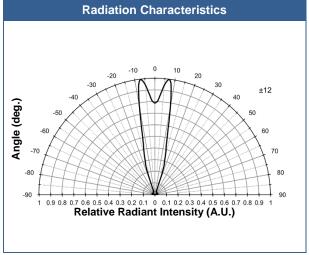
WIEDNER HAUPTSTRASSE 76 IO40 VIENNA AUSTRIA TEL. +43 I 586 52 43 -0, FAX. -44 OFFICE@ROITHNER-LASER.COM



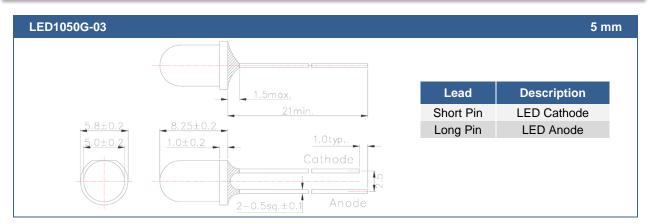








Outline Dimensions



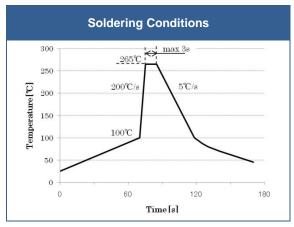
All Dimensions in mm

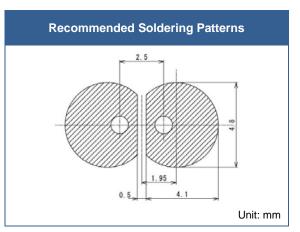
Precautions

Soldering:

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering
- Do not solder the LED closer than 3 mm from the base of the lead.

Recommended soldering conditions:





Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

Static Electricity:

LEDs are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

Radiation:

During operation these LEDs do emit light, which could be hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. Protective glasses if needed. It is further advised to attach a warning label on products/systems.

Operation:

Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device. Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

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